## General Description

The MAX120/MAX122 complete, BiCMOS, sampling 12-bit analog-to-digital converters (ADCs) combine an on-chip track/hold (T/H) and a low-drift voltage reference with fast conversion speeds and low-power consumption. The T/H's 350ns acquisition time combined with the MAX120's $1.6 \mu \mathrm{~s}$ conversion time results in throughput rates as high as 500 k samples per second (ksps). Throughput rates of 333ksps are possible with the $2.6 \mu$ s conversion time of the MAX122. The MAX120/MAX122 accept analog input voltages from -5 V to +5 V . The only external components needed are decoupling capacitors for the power-supply and reference voltages. The MAX120 operates with clocks in the 0.1 MHz to 8 MHz frequency range. The MAX122 accepts 0.1 MHz to 5 MHz clock frequencies.

The MAX120/MAX122 employ a standard microprocessor $(\mu \mathrm{P})$ interface. Three-state data outputs are configured to operate with 12-bit data buses. Data-access and busrelease timing specifications are compatible with most popular $\mu \mathrm{Ps}$ without resorting to wait states. In addition, the MAX120/MAX122 can interface directly to a first-in, first-out (FIFO) buffer, virtually eliminating $\mu \mathrm{P}$ interrupt overhead. All logic inputs and outputs are TTL/CMOS compatible. For applications requiring a serial interface, refer to the MAX121.

## Applications

- Digital-Signal Processing
- Audio and Telecom Processing
- Speech Recognition and Synthesis
- High-Speed Data Acquisition
- Spectrum Analysis
- Data Logging Systems


## Pin Configuration

| TOP VIEW |  <br> PDIP/SO/SSOP | 24 23 22 21 20 19 18 17 16 15 14 13 |
| :---: | :---: | :---: |

## Features

- 12-Bit Resolution
- No Missing Codes Over Temperature
- 20ppm $/{ }^{\circ} \mathrm{C}-5 \mathrm{~V}$ Internal Reference
- $1.6 \mu \mathrm{~s}$ Conversion Time/500ksps Throughput (MAX120)
- $2.6 \mu \mathrm{~s}$ Conversion Time/333ksps Throughput (MAX122)
- Low Noise and Distortion:
- 70dB (min) SINAD
- -77dB (max) THD (MAX122)
- Low Power Dissipation: 210 mW
- Separate Track/Hold Control Input
- Continuous-Conversion Mode Available
- $\pm 5 \mathrm{~V}$ Input Range, Overvoltage Tolerant to $\pm 15 \mathrm{~V}$
- 24-Pin Narrow DIP, Wide SO, and SSOP Packages


## Ordering Information

| PART | TEMP RANGE | PIN- <br> PACKAGE | INL <br> (LSB) |
| :--- | :---: | :--- | :---: |
| MAX120CNG + | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 PDIP | $\pm 1$ |
| MAX120CWG + | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 Wide SO | $\pm 1$ |
| MAX120CAG + | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 SSOP | $\pm 1$ |
| MAX120ENG + | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 PDIP | $\pm 1$ |
| MAX120EWG + | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 Wide SO | $\pm 1$ |

+Denotes a lead(Pb)-free/RoHS-compliant package.

## Functional Diagram



## Absolute Maximum Ratings



Narrow CDIP (derate $12.50 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ above $+70^{\circ} \mathrm{C}$ ).. .1000 mW Operating Temperature Ranges

| MAX12_C | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ |
| :---: | :---: |
| MAX12 E | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ |
| MAX12_MRG | $-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ |
| Storage Temperature Range | $-65^{\circ} \mathrm{C}$ to $+160^{\circ} \mathrm{C}$ |
| Lead Temperature (soldering, 10s) | $+300^{\circ} \mathrm{C}$ |
| Soldering Temperature (reflow). | $+260^{\circ} \mathrm{C}$ |

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## Electrical Characteristics

$\left(\mathrm{V}_{\mathrm{DD}}=+4.75 \mathrm{~V}\right.$ to $+5.25 \mathrm{~V}, \mathrm{~V}_{\mathrm{SS}}=-10.8 \mathrm{~V}$ to $-15.75 \mathrm{~V}, \mathrm{f}_{\mathrm{CLK}}=8 \mathrm{MHz}$ for MAX 120 and 5 MHz for $\mathrm{MAX} 122, \mathrm{~T}_{\mathrm{A}}=\mathrm{T}_{\mathrm{MIN}}$ to $\mathrm{T}_{\mathrm{MAX}}$, unless otherwise noted.)

| PARAMETER | SYMBOL | CONDITIONS |  | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| ACCURACY |  |  |  |  |  |  |  |
| Resolution | RES |  |  | 12 |  |  | Bits |
| Differential Nonlinearity (Note 1) | DNL | 12-bit no missing codes over temperature range | MAX122AC/AE |  |  | $\pm 3 / 4$ | LSB |
|  |  |  | $\begin{aligned} & \text { MAX120C/E, } \\ & \text { MAX122BC/BE } \end{aligned}$ |  |  | $\pm 1$ |  |
|  |  | 11-bit no missing codes over temperature range | MAX120M |  |  | $\pm 2$ |  |
| Integral Nonlinearity (Note 1) | INL |  | MAX122AC/AE |  |  | $\pm 3 / 4$ | LSB |
|  |  |  | MAX120C/E, MAX122BC/BE |  |  | $\pm 1$ |  |
| Bipolar Zero Error (Note 1) |  | Code $00 . .00$ to $00 . .01$ transition,$\text { near } \mathrm{V}_{\text {AIN }}=0 \mathrm{~V}$ |  |  |  | $\pm 3$ | LSB |
|  |  | Temperature drift |  | $\pm 0.005$ |  |  | LSB/"C |
| Full-Scale Error (Notes 1, 2) |  | Including reference zero error; $\mathrm{T}_{\mathrm{A}}=+25$ | adjusted for bipolar <br> C |  |  | $\pm 8$ | LSB |
| Full-Scale Temperature Drift |  | Excluding reference |  |  | $\pm 1$ |  | ppm/"C |
| Power-Supply Rejection Ratio (Change in FS) <br> (Note 3) | PSRR | $\mathrm{V}_{\text {DD }}$ only, $5 \mathrm{~V} \pm 5 \%$ |  |  | $\pm 1 / 4$ | $\pm 3 / 4$ | LSB |
|  |  | $\mathrm{V}_{\text {SS }}$ only, $-12 \mathrm{~V} \pm 10 \%$ |  |  | $\pm 1 / 4$ | $\pm 1$ |  |
|  |  | VSS only, $-15 \mathrm{~V} \pm 5 \%$ |  |  | $\pm 1 / 4$ | $\pm 1$ |  |
| ANALOG INPUT |  |  |  |  |  |  |  |
| Input Range |  |  |  | -5 |  | +5 | V |
| Input Current |  | $\mathrm{V}_{\text {AIN }}=+5 \mathrm{~V}$ (approximately $6 \mathrm{k} \Omega$ to REF) |  |  |  | 2.5 | mA |
| Input Capacitance (Note 4) |  |  |  |  |  | 10 | pF |
| Full-Power Input Bandwidth |  |  |  |  | 1.5 |  | MHz |
| REFERENCE |  |  |  |  |  |  |  |
| Output Voltage |  | No external load, $\mathrm{V}_{\text {AIN }}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$ |  | -5 02 |  | -4.98 | V |
| External Load Regulation |  | $0 \mathrm{~mA}<\mathrm{I}_{\text {SINK }}<5 \mathrm{~mA}, \mathrm{~V}_{\text {AIN }}=0 \mathrm{~V}$ |  |  |  | 5 | mV |
| Temperature Drift (Note 5) |  | MAX12_C/E |  |  |  | $\pm 25$ | $\mathrm{ppm} /{ }^{\circ} \mathrm{C}$ |

## Electrical Characteristics (continued)

$\left(\mathrm{V}_{\mathrm{DD}}=+4.75 \mathrm{~V}\right.$ to $+5.25 \mathrm{~V}, \mathrm{~V}_{\mathrm{SS}}=-10.8 \mathrm{~V}$ to $-15.75 \mathrm{~V}, \mathrm{f} \mathrm{CLK}=8 \mathrm{MHz}$ for MAX120 and 5 MHz for MAX122, $\mathrm{T}_{\mathrm{A}}=\mathrm{T}_{\mathrm{MIN}}$ to $\mathrm{T}_{\mathrm{MAX}}$, unless otherwise noted.)


## Timing Characteristics

$\left(\mathrm{V}_{\mathrm{DD}}=+5 \mathrm{~V}, \mathrm{~V}_{\mathrm{SS}}=-12 \mathrm{~V}\right.$ to $-15 \mathrm{~V}, 100 \%$ tested, $\mathrm{T}_{\mathrm{A}}=\mathrm{T}_{\mathrm{MIN}}$ to $\mathrm{T}_{\mathrm{MAX}}$, unless otherwise noted.) (Note 7)

| PARAMETER | SYMBOL | CONDITIONS | $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$ |  |  | MAX12_C/E |  |  | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | TYP | MAX | MIN | TYP | MAX |  |
| $\overline{\mathrm{CS}}$ to $\overline{\mathrm{RD}}$ Setup Time | $\mathrm{t}_{\mathrm{CS}}$ |  | 0 |  |  | 0 |  |  | ns |
| $\overline{\mathrm{CS}}$ to $\overline{\mathrm{RD}}$ Hold Time | $\mathrm{t}_{\mathrm{CH}}$ |  | 0 |  |  | 0 |  |  | ns |
| CONVST Pulse Width | ${ }^{\text {c }} \mathrm{CW}$ |  | 30 |  |  | 30 |  |  | ns |
| $\overline{\mathrm{RD}}$ Pulse Width | $t_{\text {RW }}$ |  | tDA |  |  | $t_{\text {DA }}$ |  |  | ns |
| Data-Access Time | $t_{\text {DA }}$ | $C_{L}=100 \mathrm{pF}$ |  | 40 | 75 |  |  | 100 | ns |
| Bus-Relinquish Time | $\mathrm{t}_{\mathrm{DH}}$ |  |  | 30 | 50 |  |  | 65 | ns |
| $\overline{\mathrm{RD}}$ or CONVST to BUSY | $\mathrm{t}_{\mathrm{B} 0}$ | $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ |  | 30 | 75 |  |  | 100 | ns |
| CLKIN to $\overline{\mathrm{BUSY}}$ or $\overline{\mathrm{NT}}$ | $\mathrm{t}_{\mathrm{B} 1}$ | $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ |  | 70 | 110 |  |  | 150 | ns |
| CLKIN to $\overline{\text { BUSY }}$ Low | $\mathrm{t}_{\mathrm{B} 2}$ | In mode 5 |  | 45 | 90 |  |  | 120 | ns |
| $\overline{\mathrm{RD}}$ to INT High | $\mathrm{t}_{\mathrm{H}}$ | $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ |  | 30 | 50 |  |  | 75 | ns |
| $\overline{\text { BUSY }}$ or INT to Data Valid | $t_{B D}$ | $\begin{aligned} & \mathrm{C}_{\mathrm{L}}(\text { Data })=100 \mathrm{pF}, \\ & \mathrm{C}_{\mathrm{L}}(\overline{\text { INT }}, \overline{\mathrm{BUSY}})=50 \mathrm{pF} \end{aligned}$ |  |  | 20 |  |  | 30 | ns |
| Acquisition Time (Note 8) | $t_{\text {ACQ }}$ |  | 350 |  |  | 350 |  |  | ns |
| Aperture Delay (Note 8) | ${ }^{\text {taP }}$ |  |  | 10 |  |  |  |  | ns |
| Aperture Jitter (Note 8) |  |  |  | 30 |  |  |  |  | ps |

Note 1: These tests are performed at $\mathrm{V}_{\mathrm{DD}}=5 \mathrm{~V}, \mathrm{~V}_{\mathrm{SS}}=-15 \mathrm{~V}$. Operation over supply is guaranteed by supply rejection tests.
Note 2: Ideal full-scale transition is at $+5 \mathrm{~V}-3 / 2 \mathrm{LSB}=+4.9963 \mathrm{~V}$, adjusted for offset error.
Note 3: Supply rejection defined as change in full-scale transition voltage with the specified change in supply voltage $=(\mathrm{FS}$ at nominal supply)- (FS at nominal supply $\pm$ tolerance), expressed in LSBs.
Note 4: For design guidance only, not tested.
Note 5: Temperature drift is defined as the change in output voltage from $+25^{\circ} \mathrm{C}$ to $\mathrm{T}_{\mathrm{MIN}}$ or $\mathrm{T}_{\text {MAX }}$. It is calculated as $\mathrm{T}_{\mathrm{C}}=\Delta \mathrm{V}_{\mathrm{REF}} /$ $V_{\text {REF }} /(\Delta T)$.
Note 6: $\mathrm{V}_{\overline{\mathrm{CS}}}=\mathrm{V}_{\overline{\mathrm{RD}}}=\mathrm{V}_{\overline{\mathrm{CONVST}}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{MODE}}=5 \mathrm{~V}$.
Note 7: Control inputs specified with $\mathrm{t}_{\mathrm{r}}=\mathrm{t}_{\mathrm{f}}=5 \mathrm{~ns}$ ( $10 \%$ to $90 \%$ of +5 V ) and timed from a 1.6 V voltage level. Output delays are measured to +0.8 V if going low, or +2.4 V if going high. For bus-relinquish time, a change of 0.5 V is measured. See Figures 1 and 2 for load circuits.
Note 8: For design guidance only, not tested.

## Pin Description

| PIN | NAME | FUNCTION |
| :---: | :---: | :--- |
| 1 | MODE | Mode Input. Hardwire to set operational mode. <br> VDD: Single conversion, $\overline{\text { INT Output }}_{\text {OPEN: Single conversion, } \overline{\text { BUSY }} \text { Output }}$ <br> DGND: Continuous conversions, $\overline{\text { BUSY }}$ Output |
| 2 | V $_{\text {SS }}$ | Negative Power Supply, -12V or -15V |
| 3 | V $_{\text {DD }}$ | Positive Power Supply, +5 V |
| 4 | AIN | Sampling Analog Input, $\pm 5 \mathrm{~V}$ bipolar input range |
| 5 | V $_{\text {REF }}$ | -5 V Reference Output. Bypass to AGND with $22 \mu \mathrm{~F} \\| 0.1 \mu \mathrm{~F}$. |

## Pin Description (continued)

| PIN | NAME | FUNCTION |
| :---: | :---: | :---: |
| 6 | AGND | Analog Ground |
| 7-11, 13-19 | D11-D0 | Three-State Data Outputs D11 (MSB) to D0 (LSB) |
| 12 | DGND | Digital Ground |
| 20 | CONVST | Convert Start Input. Initiates conversions on its falling edge. |
| 21 | CLKIN | Clock Input. Drive with TTL-compatible clock from 0.1 MHz to 8 MHz (MAX120), 0.1 MHz to 5 MHz (MAX122) |
| 22 | INT/BUSY | Interrupt or Busy Output. Indicates converter status. If MODE is connected to $V_{D D}$, configure for an $\overline{\text { INT }}$ output. If MODE is open or connected to DGND, configure for a $\overline{\mathrm{BUSY}}$ output. See operational diagrams. |
| 23 | $\overline{\mathrm{CS}}$ | Chip-Select Input, Active-Low. When $\overline{\mathrm{RD}}$ is low, enables the three-state outputs. If $\overline{\text { CONVST }}$ and $\overline{\mathrm{RD}}$ are low, a conversion is initiated on the falling edge of $\overline{\mathrm{CS}}$. |
| 24 | $\overline{\mathrm{RD}}$ | Read Input, Active-Low. When $\overline{\mathrm{CS}}$ is low, $\overline{\mathrm{RD}}$ enables the three-state outputs. If $\overline{\mathrm{CONVST}}$ and $\overline{\mathrm{CS}}$ are low, conversion is initiated on the falling egde of $\overline{R D}$. |

## Detailed Description

## ADC Operation

The MAX120/MAX122 use successive approximation and input T/H circuitry to convert an analog signal to a series of 12-bit digital-output codes. The control logic interfaces easily to most $\mu \mathrm{Ps}$, requiring only a few passive components tor most applications. The T/H does not require an external capacitor. Figure 3 shows the MAX120/MAX122 in the simplest operational configuration.

## Analog Input Track/Hold

Figure 4 shows the equivalent input circuit, illustrating the sampling architecture of the ADC's analog comparator. An internal buffer charges the hold capacitor to minimize the required acquisition time between conversions. The analog input appears as a $6 \mathrm{k} \Omega$ resistor in parallel with a 10pF capacitor.
Between conversions, the buffer input is connected to AIN through the input resistance. When a conversion starts, the buffer input disconnects from AIN, thus sampling the input. At the end of the conversion, the buffer input reconnects to AIN, and the hold capacitor once again charges to the input voltage.
The T/H is in tracking mode whenever a conversion is NOT in progress. Hold mode starts approximately 10ns after a conversion is initiated. Variation in this delay from one conversion to the next (aperture jitter) is typically 30ps. Figures 7 through 11 detail the T/H mode and interface timing for the various interface modes.


Figure 1. Load Circuits for Access Time


Figure 2. Load Circuits for Bus-Relinquish Time


Figure 3. MAX120/MAX122 in the Simplest Operational Mode (Continuous Conversion)

## Internal Reference

The MAX120/MAX122 -5.00V buried-zener reference biases the internal DAC. The reference output is available at the $\mathrm{V}_{\text {REF }}$ pin and must be bypassed to the AGND pin with a $0.1 \mu \mathrm{~F}$ ceramic capacitor in parallel with a $22 \mu \mathrm{~F}$ or greater electrolytic capacitor. The electrolytic capacitor's equivalent series resistance (ESR) must be $100 \mathrm{~m} \Omega$ or less to properly compensate the reference output buffer. Sanyo's organic semiconductor works well.
Sanyo Video Components (USA)
Phone: (619) 661-6835 FAX: (619) 661-1055
Sanyo Electric Company, LTD. (Japan)
Phone: 0720-70-1005 FAX: 0720-70-1174

## Sanyo Fisher Vertriebs GmbH (Germany)

Phone: 06102-27041, ext. 44 FAX: 06102-27045
Proper bypassing minimizes reference noise and maintains a low impedance at high frequencies. The internal reference output buffer can sink up to a 5 mA external load.
An external reference voltage can be used to overdrive the MAX120/MAX122's internal reference if it ranges from -5.05 V to -5.10 V and is capable of sinking a minimum of 5 mA . The external $\mathrm{V}_{\text {REF }}$ bypass capacitors are still required.


Figure 4. Equivalent Input Circuit

## Digital Interlace

## External Clock

The MAX120/MAX122 require a TTL-compatible clock for proper operation. The MAX120 accepts clocks in the 0.1 MHz to 8 MHz frequency range when operating in modes 1-4 (see the Operating Modes section). The maximum clock frequency is limited to 6 MHz when operating in mode 5 . The MAX122 requires a 0.1 MHz to 5 MHz clock for operation in all five modes. The minimum clock frequency for both the MAX120 and MAX122 is limited to 0.1 MHz , due to the T/H's droop rate.

## Clock and Control Synchronization

The clock and convert start inputs ( $\overline{\mathrm{CONVST}}$ or $\overline{\mathrm{RD}}$ and $\overline{\mathrm{CS}}$, see the Operating Modes section) are not synchronized, the conversion time can vary from 13 to 14 clock cycles. The successive approximation register (SAR) always changes state on the CLKIN input's rising edge. To ensure a fixed conversion time, see Figure 5 and the following guidelines.
For a conversion time of 13 clock cycles, the convert start input(s) should go low at least 50ns before CLKIN's next rising edge. For a conversion time of 14 clock cycles, the convert start input(s) should go low within 10 ns of CLKIN's next rising edge. If the convert start input(s) go low from 10ns to 50 ns before CLKIN's next rising edge, the number of clock cycles required is undefined and can be either 13 or 14 . For best analog performance, synchronize the convert start inputs with the clock input.


Figure 5. Clock and Control Synchronization


Figure 6. Data-Access and Bus-Relinquish Timing

## Output Data Format

The conversion result is output on a 12-bit data bus with a 75 ns data-access time. The output data format is twoscomplement. Three input control signals ( $\overline{\mathrm{CS}}, \overline{\mathrm{RD}}$, and CONVST $)$, the $\overline{\mathrm{INT}} / \overline{\mathrm{BUSY}}$ converter status output, and the 12 bits of output data can interface directly to a 16-bit data bus. See Figure 6 for data-access timing.

## Timing and Control

The MAX120/MAX122 have five operational modes as outlined in Figures 7 to 11 and discussed in the Operating Modes section.
Full-control mode (mode 1) provides maximum control to the user for convert start and data-read operations.
Full-control mode is for $\mu \mathrm{Ps}$ with or without wait-state capability. Stand-alone mode (mode 2) and continuousconversion mode (mode 5) are for systems without $\mu \mathrm{Ps}$,


Figure 7. Full-Control Mode (Mode 1)
or for $\mu \mathrm{P}$-based systems where the ADC and the $\mu \mathrm{P}$ are linked through first-in, first-out (FIFO) buffers or direct memory access (DMA) ports. Slow-memory mode (mode 3 ) is intended for $\mu \mathrm{Ps}$ that can be forced into a wait state during the ADC's conversion time. ROM mode (mode 4) is for $\mu$ Ps that cannot be forced into a wait state.
In all five operating modes, the start of a conversion is controlled by one of three digital inputs: $\overline{\mathrm{CONVST}}, \overline{\mathrm{RD}}$, or $\overline{\mathrm{CS}}$. Figure 12 shows the logic equivalent for the conversion circuitry. In any operating mode, $\overline{\text { CONVST must be }}$ low for a conversion to occur. Once the conversion is in progress, it cannot be restarted.
Read operations are controlled by $\overline{\mathrm{RD}}$ and $\overline{\mathrm{CS}}$. Both of these digital inputs must be low to read output data. The $\overline{\mathrm{INT}} / \overline{\mathrm{BUSY}}$ output indicates the converter's status and determines when the data from the most recent conversion is available. The MODE input configures the INT/ BUSY output as follows:

If MODE $=V_{D D}$, $\overline{\operatorname{INT} / \overline{B U S Y}}$ functions as an INTERRUPT output. In this configuration, $\overline{\operatorname{INT} / \mathrm{BUSY}}$ goes low when the conversion is complete and returns high after the conversion data has been read.
If MODE is left open or tied to DGND, $\overline{\mathrm{NT}} / \overline{\mathrm{BUSY}}$ functions as a $\overline{B U S Y}$ output. In this case, $\overline{\operatorname{INT} / \overline{B U S Y}}$ goes low at the start of a conversion and remains low until the conversion is complete and the data is available at D0-D11.


Figure 8. Stand-Alone Mode (Mode 2)

## Initialization After Power-Up

On power-up, the first MAX120/MAX122 conversion is valid if the following conditions are met:

1) Allow 14 clock cycles for the internal $T / H$ to enter the track mode, plus a minimum of 350 ns in the track mode for the data-acquisition time.
2) Make sure the reference voltage has settled. Allow 0.5 ms for each $1 \mu \mathrm{~F}$ of reference bypass capacitance ( 11 ms for a $22 \mu \mathrm{~F}$ capacitor).

## Operating Modes

## Mode 1: (Full-Control Mode)

Figure 7 shows the timing diagram for full-control mode (mode 1). In this mode, the $\mu \mathrm{P}$ controls the conversionstart and data-read operations independently.
A falling edge on CONVST places the T/H into hold mode and starts a conversion in the SAR. The conversion is complete in 13 or 14 clock cycles as discussed in the Clock and Control Synchronization section. A change in the $\overline{\mathrm{INT} / \mathrm{BUSY}}$ output state signals the end of a conversion as follows:
If MODE $=\mathrm{V}_{\mathrm{DD}}$, the end of conversion is signaled by the INT/BUSY output falling edge.
If MODE $=$ OPEN or DGND, the $\overline{\text { INT } / \overline{B U S Y}}$ output goes low while the conversion is in progress and returns high when the conversion is complete.


Figure 9. Slow-Memory Mode (Mode 3)
When the conversion is complete, the data can be read without initiating a new conversion by pulling $\overline{\mathrm{RD}}$ and $\overline{\mathrm{CS}}$ low and leaving CONVST high. To start a new conversion without reading data, $\overline{\mathrm{RD}}$ and $\overline{\mathrm{CS}}$ should remain high while CONVST is driven low. To simultaneous read data and initiate a new conversion, $\overline{\mathrm{CONVST}}, \overline{\mathrm{RD}}$, and $\overline{\mathrm{CS}}$ should all be pulled low. Note: Allow at least 350 ns for T/H acquisition time between the end of one conversion and the beginning of the next.

## Mode 2: Stand-Alone Operation (MODE $=$ OPEN, $\overline{\mathrm{RD}}=\overline{\mathrm{CS}}=\mathbf{D G N D}$ )

For systems that do not use or require full-bus interfacing, the MAX120/MAX122 can be operated in stand-alone mode directly linked to memory through DMA ports or a FIFO buffer. In stand-alone mode, a conversion is initiated by a falling edge on CONVST. The data outputs are always enabled; data changes at the end of a conversion as indicated by a rising edge on $\overline{\mathrm{INT}} / \overline{\mathrm{BUSY}}$. See Figure 8 for stand-alone mode timing.

## Mode 3: Slow-Memory Mode <br> (CONVST = GND, MODE= OPEN)

Taking $\overline{R D}$ and $\overline{C S}$ lo laces the $T / H$ into hold mode and starts a conversion. $\overline{\mathrm{INT}} / \overline{\mathrm{BUSY}}$ remains low while the conversion is in progress and can be used as a wait input to the $\mu \mathrm{P}$. Data from the previous conversion appears on the data bus until the conversion end is indicated by $\overline{\mathrm{NT} /}$ $\overline{B U S Y}$. See Figure 9 for slow-memory mode timing.


Figure 10. ROM Mode (Mode 4)


Figure 11. Continuous-Conversion Mode (Mode 5)

## Mode 4: ROM Mode <br> (MODE = OPEN, CONVST = GND)

In ROM mode, the MAX120/MAX122 behave like a fastaccess memory location avoid placing the $\mu \mathrm{P}$ into a wait state. Pulling $\overline{\mathrm{RD}}$ and $\overline{\mathrm{CS}}$ low places the T/H in hold mode, starts a conversion, and reads data from the previous conversion. Data from the first read in a sequence is often disregarded when this interface mode is used. A second read operation accesses the first conversion's result and also starts a new conversion. The time between successive read operations must be longer than the sum of the T/H acquisition time and the MAX120/MAX122 conversion time. See Figure 10 for ROM-mode timing.

## Mode 5: Continuous-Conversion Mode $\overline{(C O N V S T}=\overline{\text { RD }}=\overline{\mathbf{C S}}=\overline{\text { MODE }}=\mathbf{G N D})$

For systems that do not use or require full-bus interfacing, the MAX120/MAX122 can operate in continuous-conversion mode, directly linked to memory through DMA ports or a FIFO buffer. In this mode, conversions are performed


Figure 12. Conversion-Control Logic
continuously at the rate of one conversion for every 14 clock cycles, which includes 2 clock cycles for the T/H acquisition time. To satisfy the 350 ns minimum acquisition time requirement within 2 clock cycles, the MAX120's maximum clock frequency is 6 MHz when operating in mode 5.
The data outputs are always enabled and "new" disappears on the output bus at the end of a conversion as indicated by the $\overline{\mathrm{INT}} / \overline{\mathrm{BUSY}}$ output rising edge. The MODE input should be hard-wired to GND. Pulling $\overline{\mathrm{CS}}, \overline{\mathrm{RD}}$, or CONVST high stops conversions. See Figure 11 for continuous-conversion mode timing.

## Applications Information

## Using FIFO Buffers

Using FIFO memory to buffer blocks of data from the MAX120 reduces $\mu \mathrm{P}$ interrupt overhead time by enabling the $\mu \mathrm{P}$ to process data while the MAX120, unassisted, writes conversion results to the FIFO. To retrieve a block of data, the $\mu \mathrm{P}$ reads from the FIFO via a read-interrupt cycle. Read and write operations for the FIFO are completely asynchronous. Figure 13 shows the MAX120 operating in continuous-conversion mode (mode 5), writing data directly into the two IDT7200 $256 \times 9$ FIFO buffers at the rate of 428 ksps . The $\mu \mathrm{P}$ is interrupted to read the accumulated data by the FIFO's half-full (HF) flag approximately three times per millisecond. For operation at 500 ksps , use an 8 MHz clock, and pulse $\overline{\text { CONVST }}$ at 500 kHz . The full flag (FF) indicates that the FIFO is full. If this flag is ignored, data may be lost. If necessary, conversions can be inhibited by pulling $\overline{\mathrm{CS}}, \overline{\mathrm{RD}}$, or $\overline{\mathrm{CONVST}}$ high. The FIFO's read cycle times are as fast as 15 ns , satisfying most system speed requirements. The RESET input resets all data in the FIFO to zero.
For synchronous operation, the CONVST pin may be used to initiate conversions, as described in the Operating Modes section (Mode 2: Stand-Alone Operation).


Figure 13. Using MAX120 with FIFO Memory

## Digital-Bus Noise

If the ADC's data bus is active during a conversion, coupling from the data pins to the ADC comparator can cause errors. Using slow-memory mode (mode 3) avoids this problem by placing the $\mu \mathrm{P}$ in a wait state during the conversion. If the data bus is active during the conversion in either mode 1 or 4 , use three-state drivers to isolate the bus from the ADC.
In ROM mode (mode 4), considerable digital noise is generated in the ADC when $\overline{\mathrm{RD}}$ or $\overline{\mathrm{CS}}$ go high, disabling the output buffers after a conversion is started. This noise can cause errors if it occurs at the same instant the SAR latches a comparator decision. To avoid this problem, $\overline{R D}$ and $\overline{\mathrm{CS}}$ should be active for less than 1 clock cycle. If this is not possible, $\overline{\mathrm{RD}}$ or $\overline{\mathrm{CS}}$ should go high coinciding with CLKIN's falling edge, since the comparator output is always latched at CLKIN's rising edge

## Layout, Grounding, and Bypassing

For best system performance, use PCBs with separate analog and digital ground planes. Wirewrap boards are not recommended. The two ground planes should be tied together at the low-impedance power-supply source, as shown in Figure 14.
The board layout should ensure that digital and analog signal lines are kept separate from each other as much as possible. Do not run analog and digital (especially clock) lines parallel to one another.
The ADC's high-speed comparator is sensitive to highfrequency noise in the $V_{D D}$ and $V_{S S}$ power supplies. Bypass these supplies to the analog ground plane with $0.1 \mu \mathrm{~F}$ and $10 \mu \mathrm{~F}$ bypass capacitors. Minimize capacitor lead lengths for best noise rejection. If the +5 V power supply is very noisy, connect a $5 \Omega$ resistor, as shown in Figure 14. Figure 15 shows the negative power-supply (VSS) rejection vs. frequency. Figure 16 shows the positive power-supply ( $\mathrm{V}_{\mathrm{DD}}$ ) rejection vs. frequency, with and without the optional $5 \Omega$ resistor.


Figure 14. Power-Supply Grounding


Figure 15. VSS Power-Supply Rejection vs. Frequency

## Gain and Offset Adjustment

Figure 17 plots the bipolar input/output transfer function for the MAX120/MAX122. Code transitions occur halfway between successive integer LSB values. Output coding is two's-complement binary with 1 LSB $=2.44 \mathrm{mV}$ (10V/4096).
In applications where gain (full-scale range) adjustment is required, Figure 18's circuit can be used. If both offset and gain (full-scale range) need adjustment, either of the circuits in Figures 19 and 20 can be used. Offset should be adjusted before gain for either of these circuits.


Figure 16. VDD Power-Supply Rejection vs. Frequency
To adjust bipolar offset with Figure 19's circuit, apply $+1 / 2$ LSB ( 0.61 mV ) to the noninverting amplifier input and adjust R4 for output-code flicker between 0000 and 0000 00000001 . For full scale, apply FS - the output code flickers between 011111111110 and 01111111 1111. There may be some interaction between these adjustments. The MAX120/MAX122 transfer function used in conjunction with Figure 19's circuit is the same as Figure 17, except the full-scale range is reduced to 2.5 V .
To adjust bipolar offset with Figure 20's circuit, apply $-1 / 2$ LSB ( -1.22 mV ) at $\mathrm{V}_{\text {IN }}$ and adjust R5 for output-code flicker between 000000000000 and 000000000001 . For gain adjustment, apply -FS $+1 / 2$ LSB ( -4.9951 V ) at $\mathrm{V}_{\mathrm{IN}}$ and adjust R1 so the output code flickers between 0111 11111110 and 01111111 1111. As with Figure 20's circuit, the offset and gain adjustments may interact. Figure 21 plots the transfer function for Figure 20's circuit.

## Dynamic Performance

High-speed sampling capability and 500ksps throughput (333ksps for the MAX122) make the MAX120/MAX122 ideal for wideband-signal processing. To support these and other related applications, fast fourier transform (FFT) test techniques are used to guarantee the ADC's dynamic frequency response, distortion, and noise at the rated throughput. Specifically, this involves applying a lowdistortion sine wave to the ADC input and recording the digital conversion results for a specified time. The data is then analyzed using an FFT algorithm, which determines its spectral content.


Figure 17. Bipolar Transfer Function


Figure 18. Trim Circuit for Gain Only
ADCs have traditionally been evaluated by specifications such as zero and full-scale error, integral nonlinearity (INL), and differential nonlinearity (DNL). Such parame ters are widely accepted for specifying performance with DC and slowly varying signals, but are less useful in signal processing applications where the ADC's impact on the system transfer function is the main concern. The significance of various DC errors does not translate well to the dynamic case, so different tests are required.

## Signal-to-Noise Ratio and

## Effective Number of Bits

The signal-to-noise plus distortion ratio (SINAD) is the ratio of the fundamental input frequency's RMS amplitude to the RMS amplitude of all other ADC output signals. The output band is limited to frequencies above DC and below one-half the ADC sample rate.


Figure 19. Offset and Gain Adjustment (Noninverting)


Figure 19. Offset and Gain Adjustment (Noninverting)
The theoretical minimum ADC noise is caused by quantization error and is a direct result of the ADC's resolution: SNR $=(6.02 \mathrm{~N}+1.76) \mathrm{dB}$, where N is the number of bits of resolution. A perfect 12-bit ADC can, therefore, do no better than 74 dB . An FFT plot shows the output level in various spectral bands. Figure 22 shows the result of sampling a pure 100 kHz sinusoid at a 500 ksps rate with the MAX120.

By transposing the equation that converts resolution to SNR, we can, from the measured SINAD, determine the effective resolution (or effective number of bits) the ADC provides: $\mathrm{N}=(\mathrm{SINAD}-1.76) / 6.02$. Figure 22 shows the effective number of bits as a function of the input frequency for the MAX120. The MAX122 performs similarly.


Figure 21. Inverting Bipolar Transfer Function


Figure 22. MAX120 FFT Plot

## Total Harmonic Distortion

If a pure sine wave is sampled by an ADC at greater than the Nyquist frequency, the nonlinearities in the ADC's transfer function create harmonics of the input frequency in the sampled output data.
Total harmonic distortion (THD) is the ratio of the RMS sum of all harmonics (in the frequency band above DC and below one-half the sample rate, but not including the DC component) to the RMS amplitude of the fundamental frequency. This is expressed as follows:

$$
\mathrm{THD}=20 \log \frac{\sqrt{\mathrm{~V}_{2}^{2}+\mathrm{V}_{3}^{2}+\mathrm{V}_{4}^{2} \ldots+\mathrm{V}_{\mathrm{N}}^{2}}}{\mathrm{~V}_{1}}
$$



Figure 23. Effective Bits vs. Input Frequency
where $V_{1}$ is the fundamental RMS amplitude, and $V_{2}$ to $V_{N}$ are the amplitudes of the 2nd through $N$ th harmonics. The THD specification in the Electrical Characteristics table includes the 2nd through 5th harmonics.

## Intermodulation Distortion

If the ADC input signal consists of more than one spectral component, the ADC transfer function nonlinearities produce intermodulation distortion (IMD) in addition to THD. IMD is the change in one sinusoidal input caused by the presence of another sinusoidal input at a different frequency
If two pure sine waves of frequency fa and fb are applied to the ADC input, nonlinearities in the ADC transfer function create distortion products at sum and difference frequencies of $m f a \pm n f b$, where $m$ and $n=0,1,2,3$, etc. THD includes those distortion products with $m$ or $n$ equal to zero. Intermodulation distortion consists of all distortion products for which neither $m$ nor $n$ equal zero. For example, the $2 n d$-order IMD terms include ( $f a+f b$ ) and (fa - fb) while the 3rd-order IMD terms include ( $2 \mathrm{fa}+\mathrm{fb}$ ), ( $2 \mathrm{fa}-\mathrm{fb}$ ), (fa + 2fb), and (fa $-2 f b$ ).
If the two input sine waves are equal in magnitude, the value (in decibels) of the 2nd-order IMD products can be expressed by the following formula:

$$
\operatorname{IMD}(\mathrm{fa} \pm \mathrm{fb})=20 \log \left[\frac{\text { amplitude at }(\mathrm{fa} \pm \mathrm{fb})}{\text { amplitude at } \mathrm{fa}}\right]
$$

## Spurious-Free Dynamic Range

Spurious-free dynamic range is the ratio of the fundamental RMS amplitude to the amplitude of the next largest spectral component (in the frequency band above DC and below one-half the sample rate). Usually the next largest spectral component occurs at some harmonic of the input frequency. However, if the ADC is exceptionally linear, it may occur only at a random peak in the ADC's noise floor.

## Chip Information

PROCESS: BiCMOS

## Package Information

For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a "+", "\#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

| PACKAGE <br> TYPE | PACKAGE <br> CODE | OUTLINE <br> NO. | LAND <br> PATTERN NO. |
| :---: | :---: | :---: | :---: |
| 24 CDIP | R24-4 | $\underline{\underline{21-0045 ~}}$ | - |
| 24 PDIP | N24+3 | $\underline{\underline{21-0043}}$ | - |
| 24 SO | $\mathrm{W} 24+2$ | $\underline{21-0042}$ | $\underline{90-0182}$ |
| 24 SSOP | A24+2 | $\underline{21-0056}$ | $\underline{90-0110}$ |

## Ordering Information (continued)

| PART | TEMP RANGE | PIN- <br> PACKAGE | INL <br> (LSB) |
| :--- | :---: | :--- | :---: |
| MAX120EAG + | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 SSOP | $\pm 1$ |
| MAX122ACNG + | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 PDIP | $\pm 3 / 4$ |
| MAX122BCNG + | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 PDIP | $\pm 1$ |
| MAX122ACWG + | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 Wide SO | $\pm 3 / 4$ |
| MAX122BCWG + | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 Wide SO | $\pm 1$ |
| MAX122ACAG + | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 SSOP | $\pm 3 / 4$ |
| MAX122BCAG + | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | 24 SSOP | $\pm 1$ |
| MAX122AENG + | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 PDIP | $\pm 3 / 4$ |
| MAX122BENG + | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 PDIP | $\pm 1$ |
| MAX122AEWG + | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 Wide SO | $\pm 3 / 4$ |
| MAX122BEWG + | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 Wide SO | $\pm 1$ |
| MAX122AEAG + | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 SSOP | $\pm 3 / 4$ |
| MAX122BEAG + | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 24 SSOP | $\pm 1$ |
| MAX122BMRG- | $-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ | 24 CERDIP | $\pm 1$ |
| MAX120EVKIT-DIP $\dagger$ | $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$ | PDIP - Through Hole |  |

+Denotes a lead(Pb)-free/RoHS-compliant package.
tMAX120 EV kit can be used to evaluate the MAX122; when ordering the EV kit, ask for a free sample of the MAX122.
-Denotes a package containing lead(Pb).

## Revision History

| REVISION <br> NUMBER | REVISION <br> DATE | DESCRIPTION | PAGES <br> CHANGED |
| :---: | :---: | :--- | :---: |
| 0 | $9 / 92$ | Initial release | - |
| 1 | $3 / 12$ | Removed PDIP, CERDIP packages from Ordering Information. Updated style <br> throughout data sheet. | $1-16$ |

## Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery \& Lifecycle Information:

Maxim Integrated:
MAX120CNG+ MAX120CAG+ MAX120CAG+T MAX120CWG $\quad$ MAX120CWG+T MAX120EAG + MAX120EAG + T
MAX120ENG+ MAX120EWG+ MAX120EWG+T MAX122ACAG+ MAX122ACAG+T MAX122ACNG+
MAX122ACWG+ MAX122ACWG+T MAX122AEAG+ MAX122AEAG+T MAX122AENG+ MAX122AEWG+
MAX122AEWG+T MAX122BCAG+ MAX122BCAG+T MAX122BCNG+ MAX122BCWG+ MAX122BCWG+T
MAX122BEAG+ MAX122BEAG+T MAX122BENG+ MAX122BEWG+ MAX122BEWG+T MAX12001ETB+T

